## Nch 30V 27A Power MOSFET

V <sub>DSS</sub>	30V
R <sub>DS(on)</sub> (Max.)	8.8mΩ
I <sub>D</sub>	±27A
P <sub>D</sub>	15W

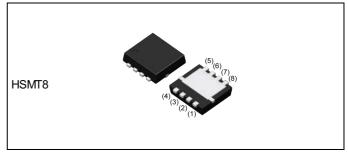
# Features

- 1) Low on resistance
- 2) High power package (HSMT8)
- 3) Pb-free lead plating; RoHS compliant
- 4) Halogen free
- 5) 100% Rg and UIS tested

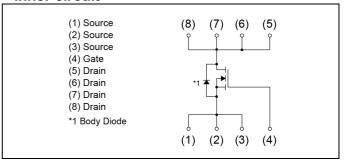
# Application

Switching

#### Outline



# ●Inner circuit



Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	330
Туре	Tape width (mm)	12
	Basic ordering unit (pcs)	3000
	Taping code	ТВ
	Marking	E120GN

# ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit	
Drain - Source voltage	V <sub>DSS</sub>	30	V	
Continuous dusin suument	T <sub>c</sub> = 25°C	I <sub>D</sub> *1	±27	Α
Continuous drain current	T <sub>a</sub> = 25°C	I <sub>D</sub>	±12	Α
Pulsed drain current	I <sub>DP</sub> *2	±48	Α	
Gate - Source voltage	$V_{GSS}$	±20	V	
Avalanche current, single pulse	I <sub>AS</sub> *3	12	Α	
Avalanche energy, single pulse	E <sub>AS</sub> *3	10	mJ	
Davier discipation	P <sub>D</sub> *1	15	W	
Power dissipation		P <sub>D</sub> *4	2.0	W
Junction temperature	T <sub>j</sub>	150	°C	
Operating junction and storage tem	perature range	T <sub>stg</sub>	-55 to +150	°C

## ●Thermal resistance

Doromotor	Currente e l	Values			I limit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub> *1	-	-	8.3	°C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub> *4	-	-	62.5	°C/W

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Davanastav	Curanh al	Conditions	Values			Linit	
Parameter	Symbol	Symbol Conditions -		Тур.	Max.	Unit	
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0V$ , $I_D = 1mA$	30	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	I <sub>D</sub> = 1mA referenced to 25°C	-	28	-	mV/°C	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 24V, V <sub>GS</sub> = 0V	1	1	1	μA	
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS}$ = ±20V, $V_{DS}$ = 0V	•	•	±100	nA	
Gate threshold voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 1mA$	1.2	-	2.5	V	
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_{j}}$	I <sub>D</sub> = 1mA referenced to 25°C	-	-3.87	-	mV/°C	
Static drain - source	D *5	V <sub>GS</sub> = 10V, I <sub>D</sub> = 12A	-	6.7	8.8	0	
on - state resistance	$R_{DS(on)}^{*5}$	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 12A	-	9.1	13.8	mΩ	
Gate resistance	$R_{G}$	f=1MHz, open drain	-	2.3	-	Ω	
Forward Transfer Admittance	Y <sub>fs</sub>  *5	V <sub>DS</sub> = 5V, I <sub>D</sub> = 12A	10.0	-	-	S	

<sup>\*1</sup> Tc = 25°C, Limited only by maximum temperature allowed.

<sup>\*2</sup> Pw $\leq$ 10 $\mu$ s , Duty cycle $\leq$ 1%

<sup>\*3</sup> L  $\simeq$  0.1mH, V<sub>DD</sub> = 15V, R<sub>G</sub> = 25 $\Omega$ , Starting T<sub>j</sub> = 25 $^{\circ}$ C Fig.3-1,3-2

<sup>\*4</sup> Mounted on a Cu board (40×40×0.8mm)

<sup>\*5</sup> Pulsed

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Daramatar	Symbol Conditions			Unit			
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Urlit	
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	590	-		
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 15V	-	160	-	pF	
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	44	-		
Turn - on delay time	t <sub>d(on)</sub> *5	V <sub>DD</sub> ≈ 15V,V <sub>GS</sub> = 10V	1	9.6	ı		
Rise time	<b>t</b> r*5	I <sub>D</sub> = 6A	ı	4.5	ı	no	
Turn - off delay time	t <sub>d(off)</sub> *5	$R_L \simeq 2.5\Omega$	-	25.5	ı	ns	
Fall time	<b>t</b> <sub>f</sub> *5	$R_G = 10\Omega$	-	3.4	-		

# • Gate charge characteristics $(T_a = 25^{\circ}C)$

Darameter	Cymah al	Conditions		Values			l limit
Parameter	Symbol			Min.	Тур.	Max.	Unit
Total gate charge	O *5		V <sub>GS</sub> = 10V	-	10	-	
Total gate charge	$Q_g$	$Q_g^{*5}$ $V_{DD} \simeq 15V$		-	4.8	-	»C
Gate - Source charge	Q <sub>gs</sub> *5	I <sub>D</sub> = 12A	V <sub>GS</sub> = 4.5V	-	2.3	-	nC
Gate - Drain charge	Q <sub>gd</sub> *5			-	1.1	-	

# ● Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Darameter	Symbol Conditions		Values			Unit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic	
Continuous forward current	I <sub>S</sub>	T <sub>a</sub> = 25°C	1	-	1.67	Α	
Pulse forward current	I <sub>SP</sub> *2	1 <sub>a</sub> - 25 C	1	-	48	Α	
Forward voltage	V <sub>SD</sub> *5	V <sub>GS</sub> = 0V, I <sub>S</sub> = 1.67A	-	-	1.2	V	
Reverse recovery time	t <sub>rr</sub> *5	I <sub>S</sub> = 12A, V <sub>GS</sub> =0V	-	21.4	-	ns	
Reverse recovery charge	Q <sub>rr</sub> *5	di/dt = 100A/μs	-	11.8	-	nC	

#### • Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

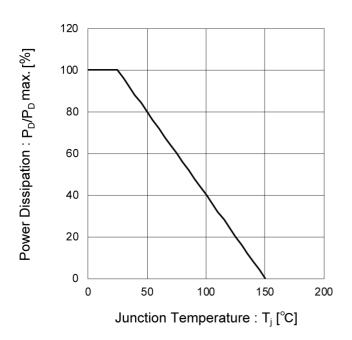
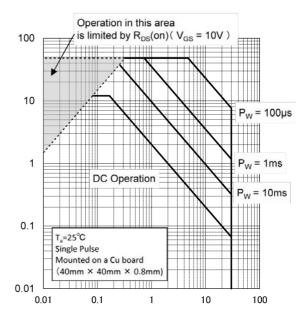


Fig.2 Maximum Safe Operating Area



Drain Current : I<sub>D</sub> [A]

Drain - Source Voltage: V<sub>DS</sub> [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

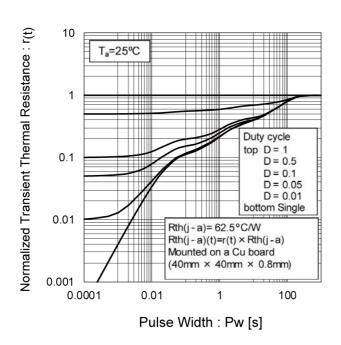
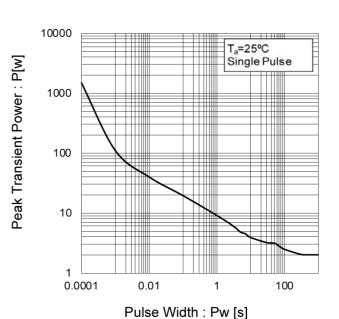


Fig.4 Single Pulse Maximum Power dissipation



Drain Current : I<sub>D</sub> [A]

## • Electrical characteristic curves

Fig.5 Typical Output Characteristics(I)

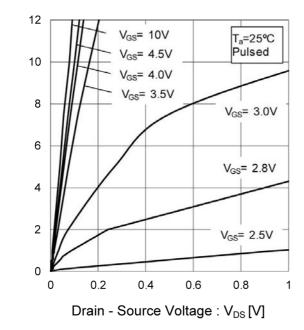
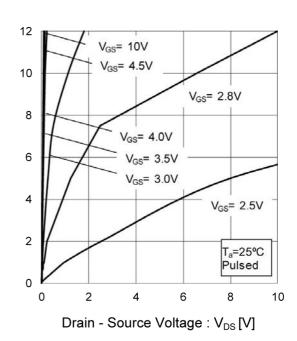


Fig.6 Typical Output Characteristics(II)



Drain Current : I<sub>D</sub> [A]

Fig.7 Breakdown Voltage vs.
Junction Temperature

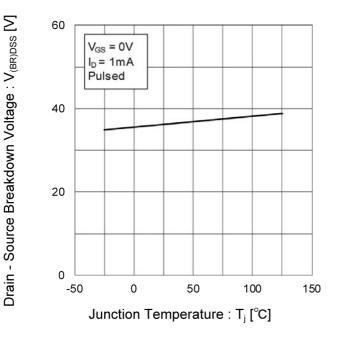
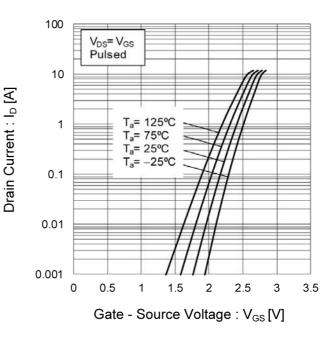


Fig.8 Typical Transfer Characteristics



Gate Threshold Voltage: V<sub>GS(th)</sub> [V]

## • Electrical characteristic curves

Fig.9 Gate Threshold Voltage vs.
Junction Temperature

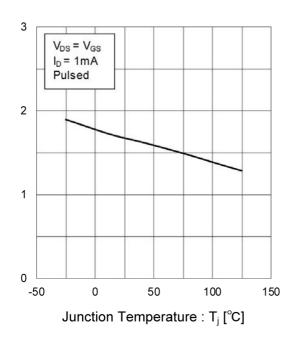


Fig.10 Forward Transfer Admittance vs.
Drain Current

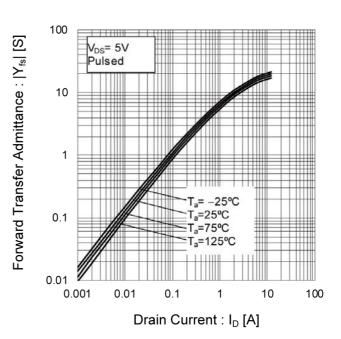


Fig.11 Drain Current Derating Curve

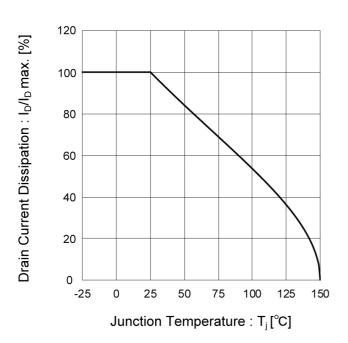
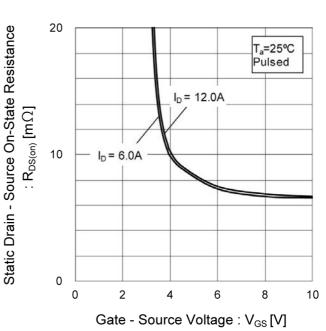


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage



## • Electrical characteristic curves

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

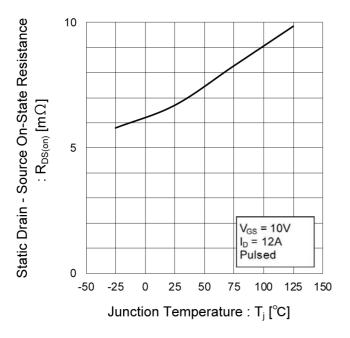


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I)

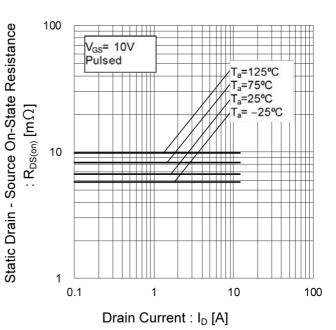
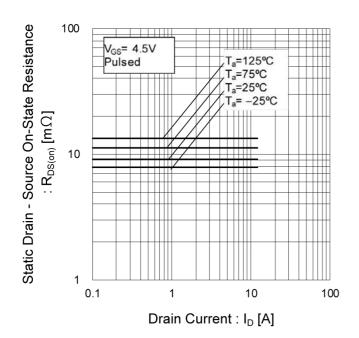


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)



# • Electrical characteristic curves

Fig.16 Typical Capacitance vs.

Drain - Source Voltage

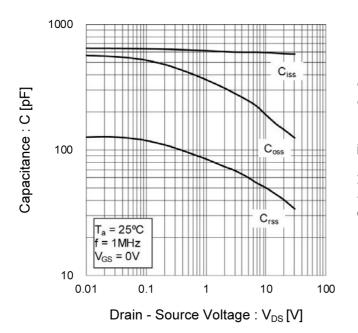


Fig.17 Switching Characteristics

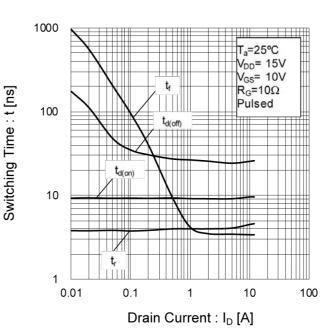


Fig.18 Dynamic Input Characteristics

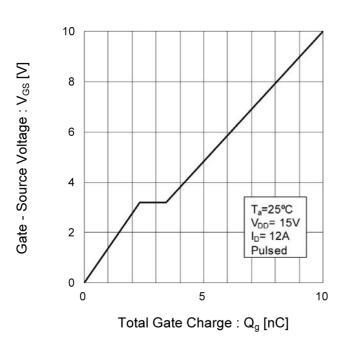
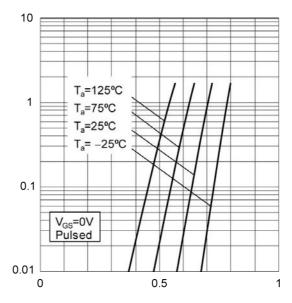


Fig.19 Source Current vs.
Source Drain Voltage



Source - Drain Voltage : V<sub>SD</sub> [V]

Source Current : Is [A]

# Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

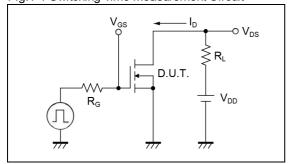


Fig.2-1 Gate Charge Measurement Circuit

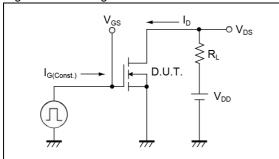


Fig.3-1 Avalanche Measurement Circuit

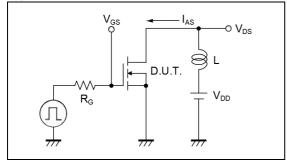


Fig.1-2 Switching Waveforms

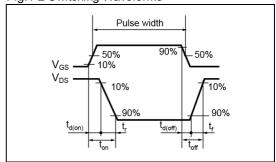


Fig.2-2 Gate Charge Waveform

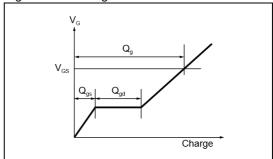
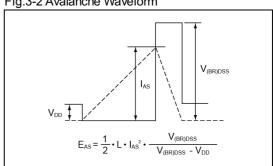


Fig.3-2 Avalanche Waveform



## Notice

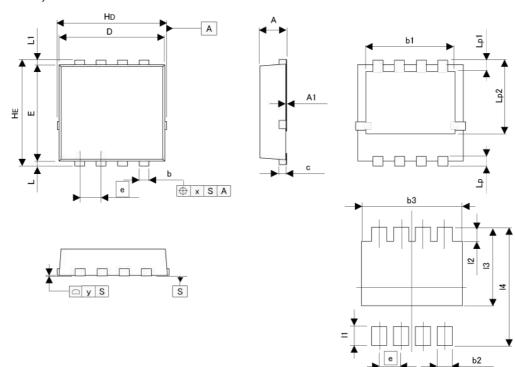
This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.



# Dimensions

# HSMT8

(3.3x3.3)



DIM	MILIME	MILIMETERS		HES
DIM	MIN	MAX	MIN	MAX
Α	0.70	0.90	0.028	0.035
A1	0.00	0.05	0.000	0.002
b	0.27	0.37	0.011	0.015
b1	2.50	2.70	0.098	0.106
С	0.10	0.30	0.004	0.012
D	3.10	3.30	0.122	0.130
E	2.90	3.10	0.114	0.122
е	0.	65	0.026	
HD	3.20	3.40	0.126	0.134
HE	3.20	3.40	0.126	0.134
L	0.07	0.25	0.003	0.010
L1	0.07	0.25	0.003	0.010
Lp	0.20	0.40	0.008	0.016
Lp1	0.25	0.45	0.010	0.018
Lp2	2.20	2.40	0.087	0.094
x		0.10		0.004
у	090	0.10		0.004

DIM -	MILIMETERS		INC	HES
DIIVI	MIN	MAX	MIN	MAX
b2	925	0.47		0.019
b3	350	2.70		0.106
11	(#)	0.50		0.020
12	(E)	0.55	9	0.022
13	90 <del>,5</del> 75	2.40	15	0.094
14	5 <b>-</b> 0	3.40	÷.	0.134

Dimension in mm/inches

Pattern of terminal position areas [Not a pattern of soldering pads]

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Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

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  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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